

IN THE CLAIMS:

mutator → 1. (Amended) A semiconductor device manufacturing method comprising the steps ~~step~~ of:
exposing a surface of a copper wiring layer to a NH₃ plasma to remove surface oxide
from the copper wiring layer;

C-2 then converting into a plasma a process gas selected from the group consisting of N₂, N₂O
and mixtures thereof; and

nitriding a surface portion of the a copper wiring layer to convert the surface portion into
a copper diffusion preventing layer by exposing the a surface of the copper wiring layer to the
process gas plasma.

2. (Previously cancelled)

mutator → 3. (Previously Amended) A semiconductor device manufacturing method according to claim 26,
wherein the hydrocarbon is CH₄ or C₂H₂.

4. (Amended) A semiconductor device manufacturing method comprising the steps ~~step~~ of:

converting to a plasma a process gas consisting of N₂ and NH₃; **and**

nitriding a surface portion of a copper wiring layer to convert the surface portion into a
copper diffusion preventing layer by exposing a surface of the copper wiring layer to the process
gas plasma; and

then forming a SiOC film on the copper wiring layer to prevent copper diffusion from the

copper wiring layer.

5. (Cancelled)

6. (Previously Amended) A semiconductor device manufacturing method according to claim 1, further comprising the step of:

forming a silicon-containing insulating film on the copper wiring layer after the surface portion of the copper wiring layer has been nitrided.

7. (Previously Amended) A semiconductor device manufacturing method according to claim 6, further comprising the steps step of:

converting a process gas containing at least one of NH_3 , N_2 , and N_2O into a second process gas plasma; and

after forming the silicon-containing insulating film, exposing the silicon-containing insulating film to the second process gas plasma.

8. (Amended) A semiconductor device manufacturing method according to claim 6, further comprising the steps step of:

forming an interlayer insulating film on the silicon-containing insulating film;

forming a via hole in the silicon-containing insulating film and the interlayer insulating film;

burying a plug connected electrically to the copper wiring layer in the via hole; and

forming an upper wiring layer, connected electrically to the plug, on the interlayer insulating film.

9. (Previously cancelled)

10. (Previously cancelled)

11. (Previously cancelled)

12. (Previously Amended) A semiconductor device manufacturing method according to claim 8, wherein the interlayer insulating film is a FSG film or a porous SiO₂ film.

13. (Cancelled)

Claims 14-25 (Previously cancelled)

26. (Amended) A semiconductor device manufacturing method comprising the ~~steps~~ step of:

exposing a surface of a copper wiring layer to a NH₃ plasma to remove surface oxide from the copper wiring layer;

then converting into a plasma a process gas made by adding a hydrocarbon C_xH_y to a gas selected from the group consisting of N₂, a hydrocarbon C_xH_y, N₂O and mixtures thereof containing said hydrocarbon; and

nitriding a surface portion of the a copper wiring layer to convert the surface portion into a copper diffusion preventing layer by exposing the a surface of the copper wiring layer to the process gas plasma.

27. (Newly added) A semiconductor device manufacturing method comprising the steps of:

C2
converting into a plasma a process gas selected from the group consisting of N_2 , N_2O and mixtures thereof;

nitriding a surface portion of a copper wiring layer to convert the surface portion into a copper diffusion preventing layer by exposing a surface of the copper wiring layer to the process gas plasma; and

then forming, on the copper wiring layer, a SiOC film for preventing copper diffusion from the copper wiring layer.

28. (Newly presented) A semiconductor device manufacturing method comprising the steps of:

converting to a plasma a process gas made by adding a hydrocarbon C_xH_y to a gas selected from the group consisting of N_2 , N_2O and mixtures thereof;

nitriding a surface portion of a copper wiring layer to convert the surface portion into a copper diffusion preventing layer by exposing the surface portion of the copper wiring layer to the process gas plasma; and

then forming, on the copper wiring layer, a SiOC film for preventing copper diffusion from the copper wiring layer.